PRODUCT SPECIFICATION

DOCUMENT NO. ENS000162240				
DESCRIPTION	**DRAWN BY**	**DESIGNED BY**	**CHECKED BY**	**APPROVED BY**
MLVS0402LAMDG Series	Sandy	JamesTeng	JamesTeng	Shawn Yeh

MLVS0402LAMDG Series Engineering Specification

1. Scope

(1) Qualified based on AEC-Q200
(2) RoHS compliant
(3) Meet IEC 61000-4-5 standard
(4) SMD type zinc oxide based ceramic chip
(5) Insulator over coat keeps excellent low and stable leakage current
(6) Quick response time (<0.5ns)
(7) High transient current capability
(8) High reliability
(9) Compact size for EIA0402

Applications

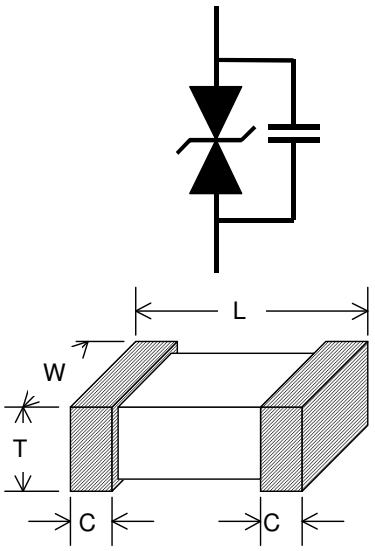
Protection against automotive related transient overvoltage

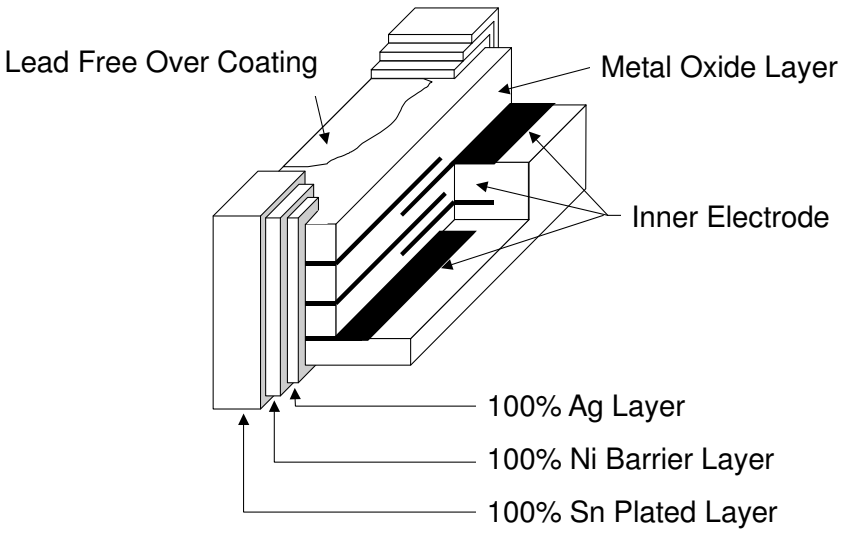
2. Explanation of Part Number

MLV	S	0402	L	AM	04	271	DG
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

1. Multilayer varistor
2. Type: S=single
3. Size
4. Lead free series
5. Automotive series
6. Max. AC voltage
7. Typical Capacitance: “271” means 27×101
8. Inpaq Control Code

3. Construction & Dimension





Unit: mm	0402
L	0.96±0.12
W	0.48±0.07
t	0.50±0.10
c	0.25±0.15

4. Part ratings and characteristics

4.1. Ratings (25°C for characteristics, 125°C for maximum ratings)

	Working voltage		Varistor voltage	Clamping Voltage	Capacitance	Peak current	Transient energy
Symbol	V_{RMS}	V_{DC}	V_V	Vc	Cp	i_{max}	W_{max}
Units	Volts (Max.)	Volts (Max.)	Volts	Volts (Max.)	pF (Typical)	Amps (Max.)	Joules (Max.)
Test Condition		< 10 µA	1mA DC	1A 8/20µs	1MHz	8/20µs	10/1000µs
MLVS0402LAM04271DG	4	5.5	7 ~ 10	22	270	10	0.04
MLVS0402LAM06161DG	6	9	11 ~ 16.5	32	160	20	0.05
MLVS0402LAM08191DG	8	11	14 ~ 17.5	35	190	20	0.05
MLVS0402LAM10131DG	11	14	18 ~ 22.5	44	130	10	0.02
MLVS0402LAM14840DG	14	18	20 ~ 26.5	45	84	20	0.05

V_{RMS} – Maximum AC operating voltage the varistor can maintain and not exceed 10µA leakage current

V_{DC} – Maximum DC operating voltage the varistor can maintain and not exceed 10µA leakage current

V_V – Voltage across the device measured at 1mA DC current. Equivalent to Vb, “Breakdown Voltage”.

Vc – Maximum peak voltage across the varistor measured at 8/20us waveform and 1A pulse current

Cp – Device capacitance measured with zero volt bias 1Vrms.

i_{max} – Maximum peak current which may be applied with 8/20us waveform without device failure

W_{max} – Maximum energy that may be dissipated with the 10/1000us waveform without device failure

5. General electrical specifications

5.1. General technical data

Operating temperature	-40 …+125°C
Storage temperature (on board)	-40… +125°C
Response time	<1 ns
Solderability	245±5°C, 5 +0/-0.5sec
Solder leach resistance	260±5°C,10 ±1sec

5.2. Storage Condition with package

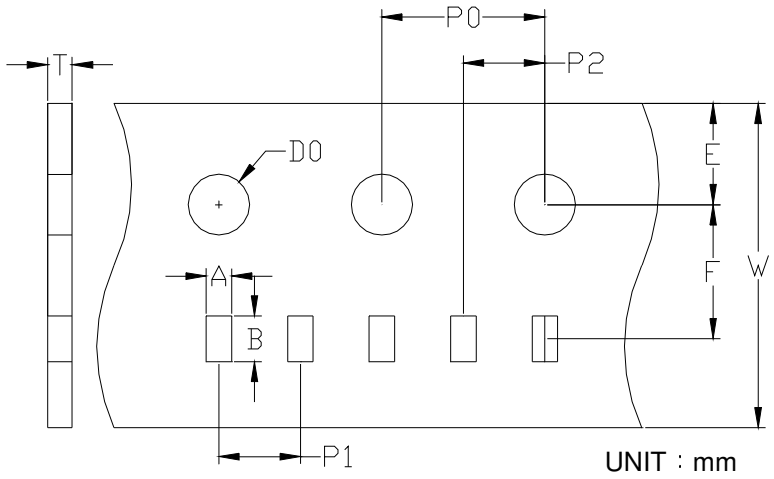
Storage Time: 12 months max

Storage Temperature: 5 to 40°C

Relative Humidity: 65% max

6. Taping Package and Label Marking

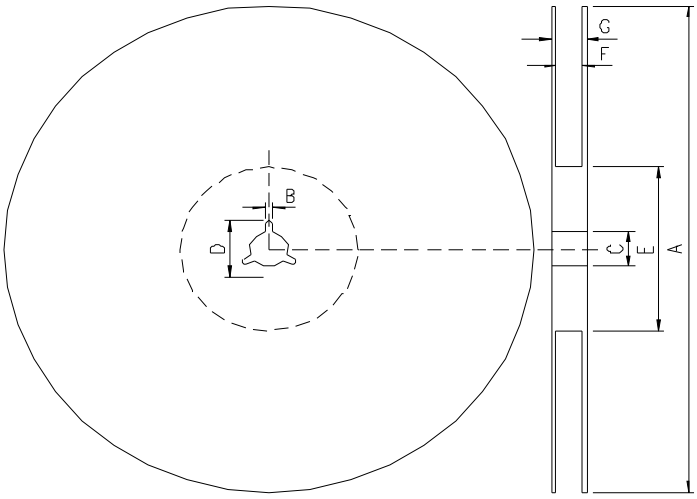
6.1. Carrier tape dimensions



UNIT: mm

Type	A	B	W	E	F	P0	P1	P2	D0	T
0402	0.59 ±0.03	1.12 ±0.03	8.0 ±0.1	1.75 ±0.05	3.5 ±0.05	4.0 ±0.1	2.0 ±0.05	2.0 ±0.05	1.55 ±0.05	0.60 ±0.03

6.2. Taping reel dimensions



UNIT: mm

A	178.0±2.0
B	2.0±0.5
C	13.0±0.5
D	21.0±0.8
E	62.0±1.5
F	9.0±0.5
G	13.0±1.0

6.3. Taping specifications

There shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the head of taping.

6.4. Label Marking

The label specified as follows shall be put on the side of reel.

(1) Part No.

(2) Quantity

(3) Lot No.

*Part No. And Quantity shall be marked on outer packaging.

6.5. Quantity of products in the taping package

(1) Standard quantity: 10,000pcs/Reel for MLVS0402LAM series

(2) Shipping quantity is a multiple of standard quantity.

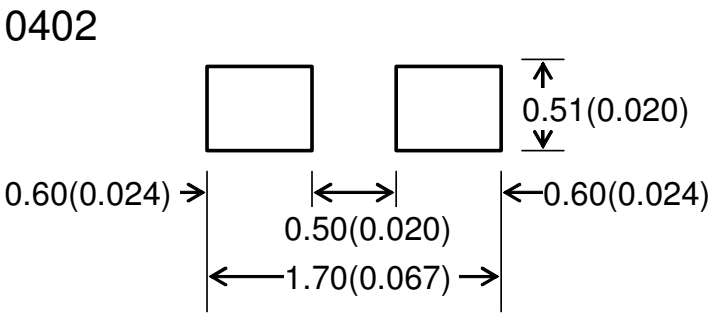
7. Precautions for Handling

7.1. Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder solder cream.

(1) Print solder in a thickness of 150 to 200 μm.

(2) Dimensions: millimeters (inches)



7.2. Precaution for handling of substrate

Do not exceed to bend the board after soldering this product extremely.

(Reference examples)

- Mounting place must be as far as possible from the position, which is close to the break line of board, or on the line of large holes of board.
- Do not bend extremely the board, in mounting another component.
  If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend using the machine or the jig to break it.

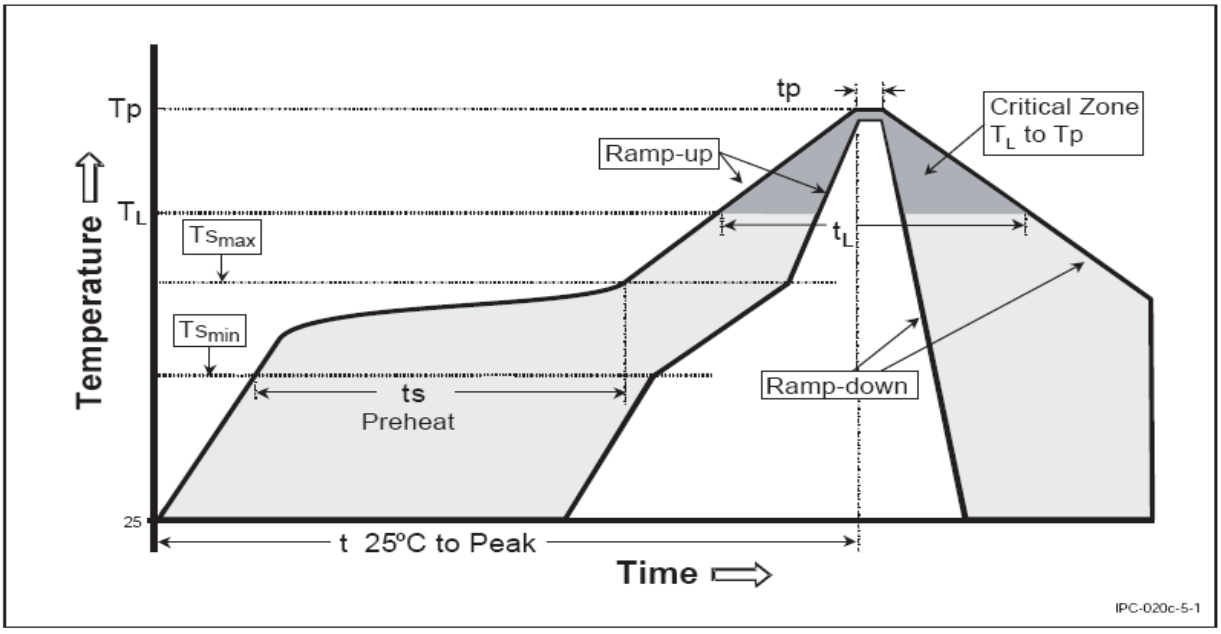
7.3. Precaution for soldering

Note that rapid heating, rapid cooling or local heating will easily damage this product.

Do not give heat shock over 100°C in the process of soldering. We recommend taking preheating and gradual cooling.

7.4. Recommendable reflow soldering

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3°C/second max.
Preheat – Temperature Min (Tsmin) – Temperature Max (Tsmax) – Time (tsmin to tsmax)	 150℃ 200℃ 60-180 seconds
Time maintained above: – Temperature (TL) – Time (tL)	 217℃ 60-150 seconds
Peak/Classification Temperature (Tp)	260℃
Time within 5 ℃ of actual Peak Temperature (tp)	 20-40 seconds
Ramp-Down Rate	6℃/second max.
Time 25 ℃ to Peak Temperature	8 minutes max.



*According to J-STD-020C

7.5. Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

(1) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun less than 30 W.

(2) The soldering gun tip shall not touch this product directly.

7.6. Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.